

SERIES 58

BOND HEADS

BETTER.
FASTER.
SMARTER.

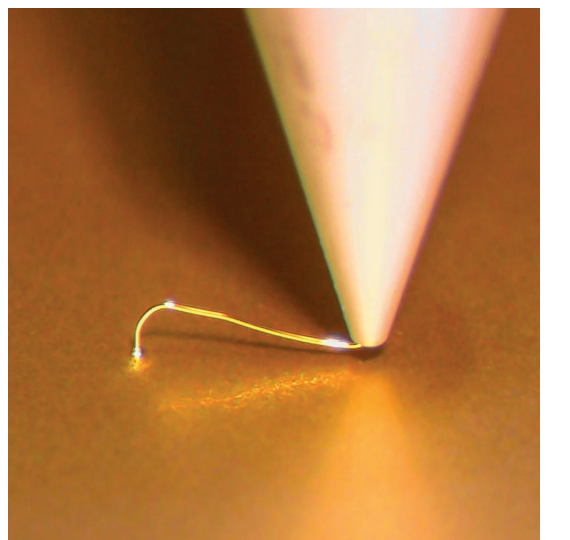


58
SERIES

FMS
BONDTEC

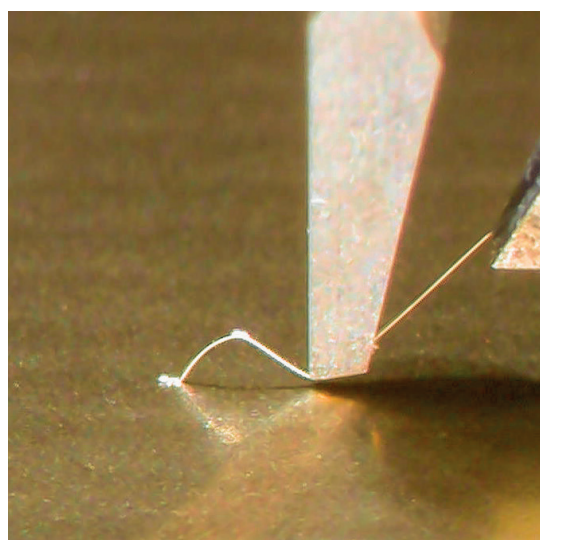
5810 – Gold Ball

- » Gold-Ball-Bonding for wires from 12 to 50 μm diameter
- » Standard-Capillaries 16 mm to 19 mm
- » Bumping, Safety-Bump, Stitch-on-Ball



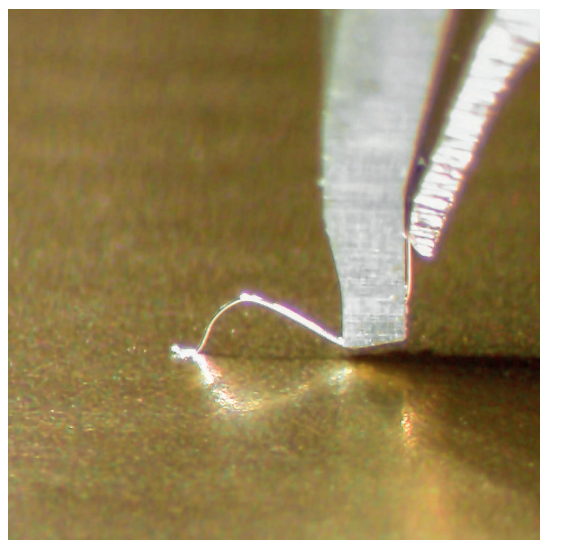
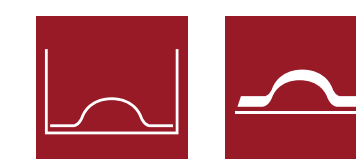
5830 – Wedge - Wedge

- » Wedge-Wedge-Bonding using 1" Tools Aluminum and Gold wires from 17.5 to 75 μm
- » 45° wire guide, retrofittable to 30° und 60°



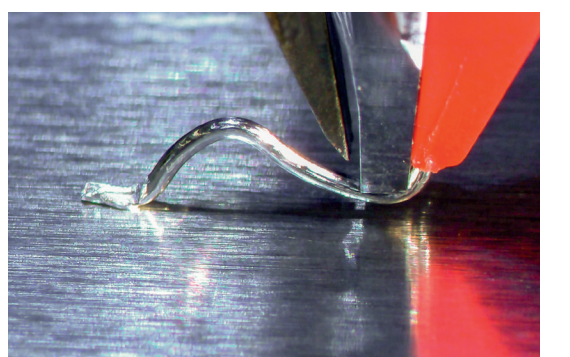
5832 – Deep Access

- » Wedge-Wedge-bonding using 1" oder $\frac{3}{4}$ " Tools
- » 90° wire guide for Aluminum and Gold wires from 12 to 75 μm and ribbon up to 250x25 μm
- » Perfect for difficult and constrictet bonding geometry



5850 – Heavy Wire

- » Wedge-Wedge-bonding for heavy wire from 100 up to 500 μm diameter // Copper from 100 up to 300 μm



5850_{HR} – Heavy Ribbon

- » Wedge-Wedge-bonding for Aluminum ribbon until 2 mm

